

Attorney Docket No.: YO997-211US2
20140-00216-US2
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Sung K. Kang

Application No.: 10/036,462

Group Art Unit: 2826

Filed: January 7, 2002

Examiner: A. Williams

For: INTERCONNECTIONS WITH
ELECTRICALLY CONDUCTIVE
ADHESIVES: STRUCTURE, MATERIALS
METHOD AND THEIR APPLICATIONS

AMENDMENT UNDER 37 C.F.R. 1.312

Box Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Dear Sir:

Please amend the above-identified U.S. patent application as follows:

FAX RECEIVED

IN THE CLAIMS:

JUN 17 2003

TECHNOLOGY CENTER 2800

Please AMEND claim 32 as follows:

32. (Currently Amended) A structure comprising:

a plurality of electrically conducting beam leads in an array on an electronic chip carrier of a TAB package used for electrically connecting between an active matrix liquid crystal display (AMLCD) and a printed circuit board;

said beam leads being electrically and mechanically joined to the electrodes on an AMLCD glass plate by means of an electrically conducting adhesive;